

**In the Claims:**

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (Currently Amended) A polyimide film obtainable by reacting an aromatic diamine having a benzoxazole structure with an aromatic ~~tetracarbonic~~ tetracarboxylic acid anhydride, which film has a planar orientation coefficient of 0.79-0.89 as measured by an X-ray diffraction method and a dielectric constant of 2.7-3.1 at 100 GHz as measured by a cavity resonance perturbation method.

2. (Original) The polyimide film of claim 1, having a dielectric loss tangent at 100 GHz of 0.0001-0.03 as measured by the cavity resonance perturbation method.

3. (Previously Presented) The polyimide film of claim 1, having dielectric constants of 2.7-3.1 at 1 GHz and 2.6-3.0 at 100 GHz, as measured by the cavity resonance perturbation method.

4. (Previously Presented) The polyimide film of claim 1, which has a density of 1.47 g/cm<sup>3</sup> - 1.55 g/cm<sup>3</sup>.

5. (Currently Amended) A polyimide film obtainable by reacting an aromatic diamine having a benzoxazole structure with an aromatic ~~tetracarbonic~~ tetracarboxylic acid anhydride, wherein the amount of water vaporized at a high temperature during heating at 500°C for 10 sec of the film immediately after helium purge at 170°C for 7 min and preliminary drying is not more than 5000 ppm.

6. (Previously Presented) The polyimide film of claim 1, wherein the ratio ( $\epsilon_{65}/\epsilon_D$ ) of the dielectric constant  $\epsilon_{65}$  at 100 GHz of the film humidity-conditioned under a constant temperature and humidity conditions of 20°C, 65% RH for 94 hr, as measured by the cavity resonance perturbation method, to the dielectric constant  $\epsilon_D$  at 100 GHz of the film vacuum dried under the conditions of 120°C, for 24 hr, as measured by the cavity resonance perturbation method, is within the range of 1.00-1.10.

7. (Currently Amended) A polyimide film obtainable by reacting an aromatic diamine having a benzoxazole structure with an aromatic ~~tetra~~carbonic tetracarboxylic acid anhydride, wherein the absolute value of the difference between a surface planar orientation degree of one surface (surface A) and a surface planar orientation degree of the other surface (surface B) of the film is 0-2.

8. (Previously Presented) The polyimide film of claim 7, wherein the surface planar orientation degree of the film surface having a higher surface planar orientation degree is not more than 15.

9. (Previously Presented) The polyimide film of claim 7, which has a curling degree of 0%-5%.

10. (Canceled)

11. (Previously Presented) A base substrate for printed wiring assemblies, which comprises the polyimide film of claim 1.

12. (Currently Amended) A method of producing a polyimide film, which comprises reacting an aromatic diamine with an aromatic ~~tetra~~carbonic tetracarboxylic acid anhydride to give a polyamide acid, casting a solution thereof on a support and drying the solution to give a self-supporting polyimide precursor film and polyimidating said precursor film, wherein the polyimide precursor film satisfies the relationships shown by the following formulas between an imidation rate  $A_{im}$  of one surface side (surface A side) and an imidation rate  $B_{im}$  of the other surface side (surface B side) of the polyimide precursor film and said polyimide precursor film is subjected to imidation:

$$\text{formula 1: } |A_{im}-B_{im}| \leq 5$$

$$\text{formula 2: } 0 \leq A_{im} \leq 15$$

$$\text{formula 3: } 0 \leq B_{im} \leq 15.$$

13. (Previously Presented) The polyimide film of claim 2, having dielectric constants of 2.7-3.1 at 1 GHz and 2.6-3.0 at 100 GHz, as measured by the cavity resonance perturbation method.

14. (Previously Presented) The polyimide film of claim 2, which has a density of 1.47 g/cm<sup>3</sup> - 1.55 g/cm<sup>3</sup>.

15. (Previously Presented) The polyimide film of claim 7, wherein the ratio ( $\epsilon_{65}/\epsilon_D$ ) of the dielectric constant  $\epsilon_{65}$  at 100 GHz of the film humidity-conditioned under a constant temperature and humidity conditions of 20°C, 65% RH for 94 hr, as measured by the cavity resonance perturbation method, to the dielectric constant  $\epsilon_D$  at 100 GHz of the film vacuum dried under the conditions of 120°C, for 24 hr, as measured by the cavity resonance perturbation method, is within the range of 1.00-1.10.

16. (Previously Presented) The polyimide film of claim 8, which has a curling degree of 0%-5%.

17. (Previously Presented) A base substrate for printed wiring assemblies, which comprises the polyimide film of claim 4.

18. (Previously Presented) A base substrate for printed wiring assemblies, which comprises the polyimide film of claim 5.

19. (Previously Presented) A base substrate for printed wiring assemblies, which comprises the polyimide film of claim 7.